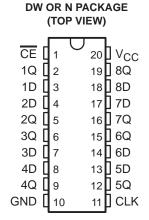
SDFS018D - D2932, MARCH 1987 - REVISED OCTOBER 1993

- Contains Eight D-Type Flip-Flops With Single-Rail Outputs
- Clock Enable Latched to Avoid False Clocking
- Applications Include: Buffer/Storage Registers Shift Registers Pattern Generators
- Buffered Common Enable Input
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs



#### description

The SN74F377A is a monolithic, positive-edge-triggered, octal, D-type flip-flop with clock enable inputs. The SN74F377A features a latched clock enable (CE) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if  $\overline{\text{CE}}$  is low. Clock triggering occurs at a particular voltage level and is not directly related to the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the  $\overline{\text{CE}}$  input.

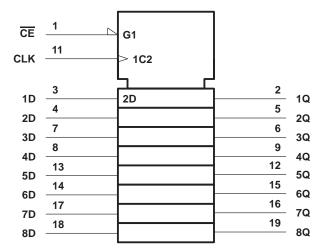
The SN74F377A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

	INPUTS		OUTPUT
CE	CLK	D	Q
Н	Х	Х	Q <sub>0</sub>
L	$\uparrow$	Н	Н
L	$\uparrow$	L	L
Х	L	Χ	Q <sub>0</sub>

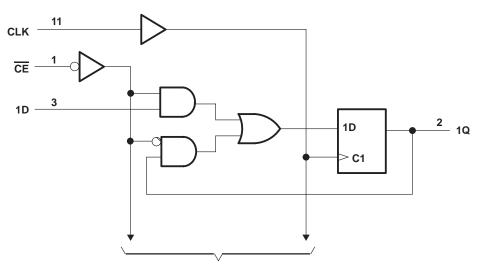


## logic symbol<sup>†</sup>



<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



To Seven Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	1.2 V to 7 V
Input current range	-30 mA to 5 mA
Voltage range applied to any output in the high state	$\sim$ -0.5 V to V <sub>CC</sub>
Current into any output in the low state	40 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	. −65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input-voltage ratings may be exceeded provided the input-current ratings are observed.



### recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
lik	Input clamp current			- 18	mA
loh	High-level output current			- 1	mA
lOL	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				UNIT
Vari	$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = - 1 mA	2.5	3.4		V
Voн	$V_{CC} = 4.75 V$ ,	I <sub>OH</sub> = - 1 mA	2.7			V
VOL	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5	V
Ι <sub>Ι</sub>	$V_{CC} = 0$ ,	V <sub>I</sub> = 7 V			0.1	mA
lін	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.5 V			- 0.6	mA
los <sup>‡</sup>	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 0	- 60		- 150	mA
ГССН	$V_{CC} = 5.5 \text{ V},$	See Note 2		55	72	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	See Note 3		70	90	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### timing requirements

			V <sub>CC</sub> =	= 5 V, 25°C	V <sub>CC</sub> = 4.5 T <sub>A</sub> = MIN t	V to 5.5 V, o MAX§	UNIT
			MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency		0	110	0	110	MHz
t <sub>W</sub>	Pulse duration		4		5		ns
		Data high or low	2		2		
t <sub>su</sub>	Setup time before CLK↑	CE high	2.5		2.5		ns
		CE low	4		4.5		1
4.	Hald far after OUK	Data high or low	1		1		
th	Hold time after CLK↑	CE high or low	0		0		ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>‡</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTES: 2. I<sub>CCH</sub> is measured after applying a momentary ground, then 4.5 V, to the clock input with all data inputs at 4.5 V and the enable input at GND

<sup>3.</sup> I<sub>CCL</sub> is measured after applying a momentary ground, then 4.5 V, to the clock input with all data and enable inputs at GND.

## **SN74F377A OCTAL D-TYPE FLIP-FLOP** WITH CLOCK ENABLE SDFS018D – D2932, MARCH 1987 – REVISED OCTOBER 1993

## switching characteristics (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TO $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$		V <sub>CC</sub> = 4.5 C <sub>L</sub> = 50 pl R <sub>L</sub> = 500 Ω T <sub>A</sub> = MIN 1	UNIT		
f <sub>max</sub>			110	125		110		MHz
<sup>t</sup> PLH	CLK	Any Q	4	6.5	8.5	4	10	ns
<sup>t</sup> PHL	OLK	Ally Q	4	7	9	4	10.5	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 4: Load circuit and waveforms are shown in Section 1.







.com 10-May-2007

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74F377ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F377ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F377ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F377ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F377ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F377AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F377ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

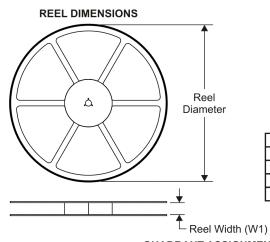
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F377ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1





#### \*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74F377ADWR	SOIC	DW	20	2000	346.0	346.0	41.0

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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